

## K3845-VB Datasheet

N-Channel 60 V (D-S) MOSFET

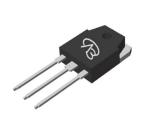
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.0028			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.0040			
I <sub>D</sub> (A)	210			
Configuration	Single			

#### FEATURES

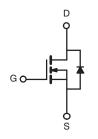
- Halogen-free According to IEC 61249-2-21
  Definition
- Trench Power MOSFET
- Package with Low Thermal Resistance
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC







TO-3P



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25 \text{ °C}$ , unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	V <sub>GS</sub> ± 20		
Continuous Drain Current	T <sub>C</sub> = 25 °C		210		
	T <sub>C</sub> = 125 °C	Ι <sub>D</sub>	120 <sup>a</sup>		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	120 <sup>a</sup>	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	480		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	75		
Single Pulse Avalanche Energy	L = 0.1 MH	E <sub>AS</sub>	281	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	P	375	W	
	T <sub>C</sub> = 125 °C	P <sub>D</sub>	125	vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)			0.4	0/10	

#### Notes

a. Package limited.

b. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$ 

c. When mounted on 1" square PCB (FR-4 material).

d. Parametric verification ongoing.

<b>SPECIFICATIONS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0, I_D = 250 \ \mu A$		60	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2.0	2.5	v
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	-	± 100	nA
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1.0	μA
	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	350	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	120	-	-	А
		$V_{GS} = 10 V$	I <sub>D</sub> = 30 A	-	0.0028	-	Ω
Drain-Source On-State Resistance <sup>a</sup>	P	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	0.0060	-	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	0.0080	-	
		$V_{GS} = 4.5 V$	I <sub>D</sub> = 20 A	-	0.0040	-	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		-	109	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		V <sub>DS</sub> = 25 V, f = 1 MHz	-	7300	9125	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	935	1170	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	647	810	
Total Gate Charge <sup>c</sup>	Qg		V <sub>DS</sub> = 30 V, I <sub>D</sub> = 110 A	-	184	276	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V		-	24.7	-	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	50.4	-	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		0.5	1.1	1.6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD}=30~V,~R_L=0.27~\Omega$ $I_D\cong110~A,~V_{GEN}=10~V,~R_g=2.5~\Omega$		-	19	29	- ns
Rise Time <sup>c</sup>	t <sub>r</sub>			-	23	35	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	83	125	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	35	53	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>				•		
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	480	А
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0		-	0.9	1.5	V
-		<u> </u>					

Notes

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

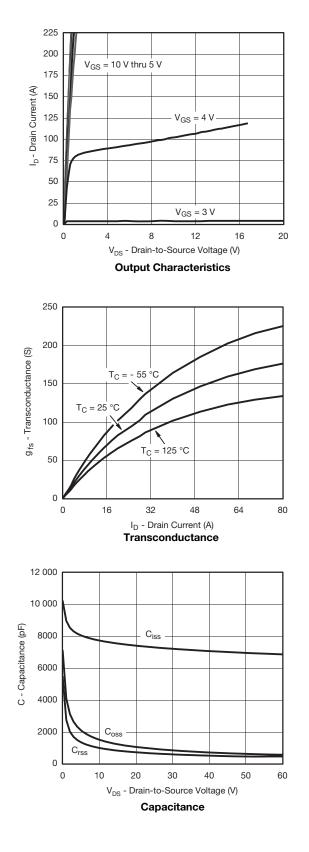
c. Independent of operating temperature.

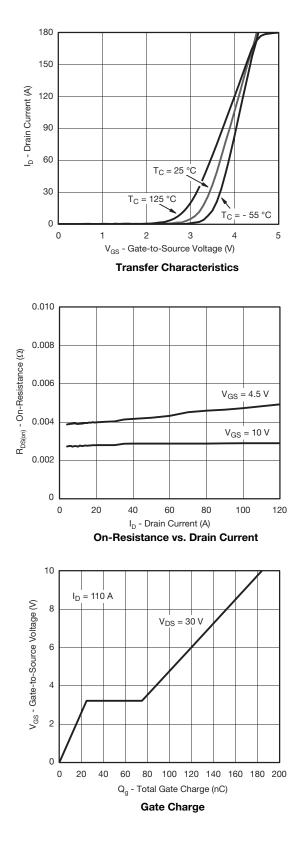
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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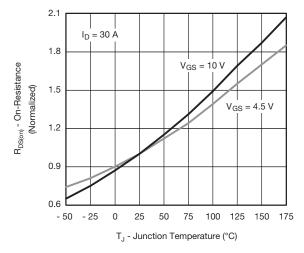
### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



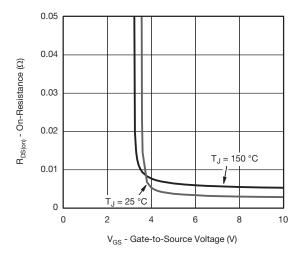




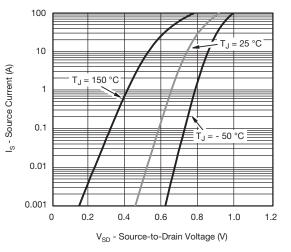
## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



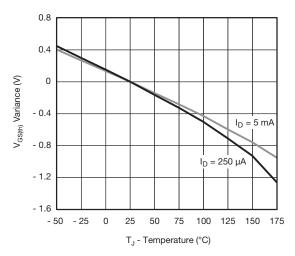




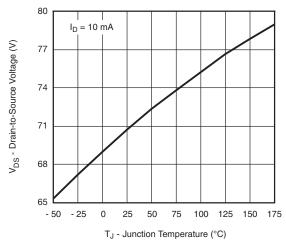
**On-Resistance vs. Gate-to-Source Voltage** 



Source Drain Diode Forward Voltage



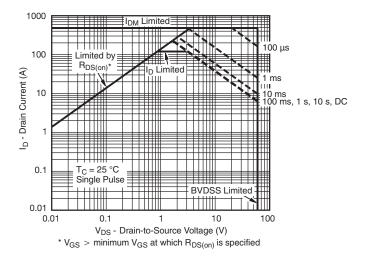




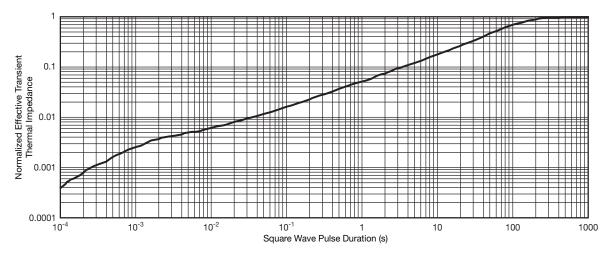
Drain Source Breakdown vs. Junction Temperature



#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



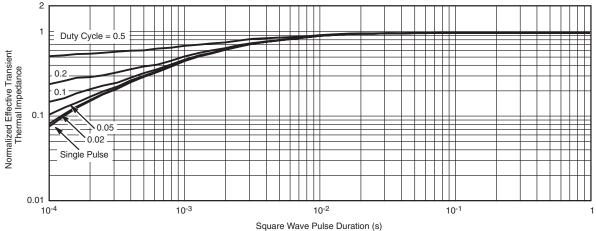
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Square wave Fulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

• The characteristics shown in the two graphs

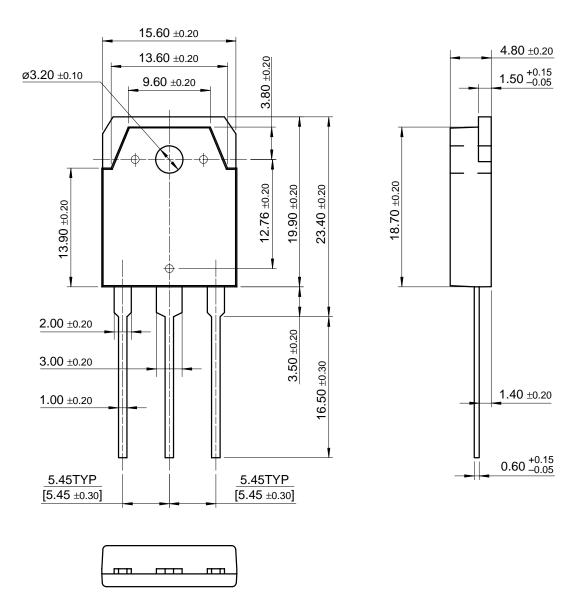
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-3P





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